Amendments to the Claims:

The **Listing of Claims** below replaces all prior versions, and listings, of Claims in the Application.

Listing of Claims:

1. (amended) A circuitized substrate comprising:

first and second ~~at least one~~ dielectric [[layer]] layers, each of said first and second dielectric layers having first and second opposing sides;

a substantially solid conductive ground plane located [[on]] between said first opposing side of said first dielectric layer and said first opposing side of said second dielectric layer;

a first ~~at least one~~ conductive signal line located on said second opposing side of said first dielectric layer and a second conductive line located on said second opposing side of said second dielectric layer; [[and]]

first and second conductive ground lines located on said second opposing side of said first dielectric layer on opposite sides of said ~~at least one~~ first conductive signal line and electrically coupled to said substantially solid conductive ground plane located on said first opposing side of said dielectric layer ; and

a first conductive thru-hole extending through said substantially solid conductive ground plane and electrically coupling said first conductive signal line to said second conductive signal line, said first and second conductive ground lines and said substantially conductive ground plane providing shielding for said at least

one conductive signal line during the passage of electrical current through said signal line.

2. (amended) The circuitized substrate of claim 1 wherein said first and second dielectric [[layer]] layers are each [[is]] selected from the group consisting of fiberglass-reinforced polymer resin, Teflon and Driclad and combinations thereof.

3. (amended) The circuitized substrate of claim 1 wherein said ~~at least one~~ substantially solid conductive ground plane is comprised of copper.

4. (amended) The circuitized substrate of claim [[one]] 1 wherein each of said ~~at least one~~ first and second conductive signal [[line]] lines is comprised of copper.

5. (amended) The circuitized substrate of claim 1 wherein said first and second conductive ground lines are each comprised of copper.

6. (amended) The circuitized substrate of claim 1 further including [[first,]] second and third conductive thru-holes, said [[first]] second and third conductive thru-holes electrically coupling said first and second conductive ground lines to said substantially solid conductive ground plane, respectively.

7 and 8 (cancelled)

9. (original) The circuitized substrate of claim 1 further including additional dielectric and conductive layers as part thereof.

10. (original) The circuitized substrate of claim 9 further including first and second pluralities of external conductive pads located on opposite sides of said circuitized substrate for electrically coupling said circuitized substrate to external electrical components.

11. (original) The invention of claim 10 wherein said circuitized substrate is a chip carrier.

12. (original) The invention of claim 10 wherein said circuitized substrate is a printed circuit board.

13. (amended) ~~An electrical assembly comprising: an electrical component; and printed circuit board including a circuitized substrate having at least one dielectric layer having first and second opposing sides, a conductive ground plane located on said first opposing side of said dielectric layer, at least one conductive signal line located on said second opposing side of said dielectric layer, and first and second conductive ground lines located on said second opposing side of said dielectric layer on opposite sides of said at least one conductive signal line and electrically coupled to said ground plane located on said first opposing side of said dielectric layer, said first and second conductive ground lines providing shielding for said at least one conductive signal line during the passage of electrical current through said signal line, said electrical component being electrically coupled to said printed circuit board~~ The circuitized substrate of claim 1 further including a third conductive signal line positioned on said second opposing side of said first dielectric layer adjacent said first conductive signal line, said first and second conductive ground lines and said substantially solid conductive ground plane also providing shielding for said third conductive signal line during the passage of electrical current through said third conductive signal line .

14. (amended) The ~~electrical assembly~~ circuitized substrate of claim 13 ~~wherein said electrical component is a chip carrier~~ further including a conductive ground line positioned on said second opposing side of said first dielectric layer substantially between said first and third conductive signal lines, said conductive ground line also providing shielding for said first and third conductive signal lines during the passage of electrical current through said first and third conductive signal lines .

15. (amended) The ~~electrical assembly~~ circuitized substrate of claim 1 ~~13 wherein said electrical component is a semiconductor chip~~ further including third and fourth dielectric layers positioned on said first and second dielectric layers, respectively, and second and third substantially solid conductive ground planes positioned on said third and fourth dielectric layers, respectively, said second and third substantially solid conductive ground planes also providing shielding for said at least one conductive signal line during the passage of electrical current through said signal line.

16 – 21 (cancelled).

Please add the following ***new*** claims:

22. (new) An electrical assembly comprising:

an electrical component; and

a printed circuit board including a circuitized substrate having first and second dielectric layers, each of said first and second dielectric layers having first and second opposing sides, a substantially solid conductive ground plane located between said first opposing side of said first dielectric layer and said first opposing side of said second dielectric layer, a first conductive signal line located on said second opposing side of said first dielectric layer and a second conductive

line located on said second opposing side of said second dielectric layer; first and second conductive ground lines located on said second opposing side of said first dielectric layer on opposite sides of said first conductive signal line and electrically coupled to said substantially solid conductive ground plane located on said first opposing side of said dielectric layer, and a first conductive thru-hole extending through said substantially solid conductive ground plane and electrically coupling said first conductive signal line to said second conductive signal line, said first and second conductive ground lines and said substantially conductive ground plane providing shielding for said at least one conductive signal line during the passage of electrical current through said signal line, said electrical component being electrically coupled to said printed circuit board.

23. (new) The electrical assembly of claim 22 wherein said electrical component is a chip carrier.

24. (new) The electrical assembly of claim 22 wherein said electrical component is a semiconductor chip.

25. (new) The electrical assembly of claim 22 wherein said circuitized substrate further includes second and third conductive thru-holes, said second and third conductive thru-holes electrically coupling said first and second conductive ground lines to said substantially solid conductive ground plane.